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Vickie Ishimaru Jan. 9, 2005
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Docket No.: F0361.C1.D1

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<i>In re</i> Application of:	Steven C. Avanzino, et al.	Confirmation No.:	7845
Serial No.:	10/608,883	Art Unit:	2813
Filed:	6/26/2003	Examiner:	Stephen W. Smoot
For:	INTEGRATED CIRCUIT WITH DIELECTRIC DIFFUSION BARRIER LAYER FORMED BETWEEN INTERCONNECTS AND INTERLAYER DIELECTRIC LAYERS	:	

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RESPONSE /AMENDMENT AFTER FINAL REJECTION
UNDER 37 C.F.R. §1.116

Sir:

The following Amendment and Remarks are submitted under 37 C.F.R. §1.116 in response to the Office Action mailed 11/10/2004, following the amendment format set forth under 37 CFR §1.121. After this introductory section, there are Amendments to the Specification and then Remarks, each starting on a separate page.

The Cross Reference to Related Applications section of the Specification has been amended to correct the serial number of the priority application.